



Our File: FLEX-6308

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#14 / Response  
7/2/03  
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Applicant: Pennace et al.

Group No: 2831

Serial No.: 10/017,490

Examiner: Chau N. Nguyen

Filed: 12/14/2001

For: CONDUCTIVE COMPOSITE  
FORMED OF A THERMOSET  
MATERIAL

**Box Non-Fee Amendment**  
**Commissioner for Patents**  
**Alexandria, VA 22313-1450**

**Sir:**

**RESPONSE**

This is in response to the office action mailed on April 2, 2003.

Claims 1, 2 and 12 stand rejected under 35 U.S.C. 102(b) as being anticipated by Wagner (WO97/37054), and claims 3, 5-8 and 11 stand rejected under 35 U.S.C. 103(a) as being unpatentable over the same reference.

These rejections are rooted in the Examiner's conclusion that Wagner teaches or suggests an adhesive interlayer.

-- having elastic properties sufficient to accommodate relative movement between the thus adhered films occasioned by flexure of the composite --  
(Office action, paragraph 2).

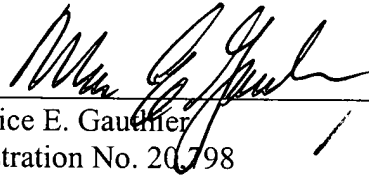
But, as explained in the accompanying declaration of John R. Pennace, one of the inventors of the present application, Wagner neither teaches nor suggests the use of elastomeric adhesives or the layers. Elastomeric adhesives would be highly permeable and thus totally unsuited for inclusion in a composite specifically designed to provide improved barrier

characteristics. Moreover, elastomeric materials with melt indexes low enough to provide interlayer slip would tend to migrate to the surfaces of the composite, and thus would not be suitable for tie layers.

It is respectfully submitted, therefore, that rather than providing support for the Examiner's rejection, Wagner actually teaches away from the present invention.

Reconsideration and allowance is respectfully requested.

Respectfully submitted,



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